LT1004-1.2, LT1004-2.5 MICROPOWER INTEGRATED VOLTAGE REFERENCES

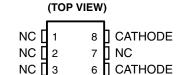
ANODE [

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- Initial Accuracy
 - $-\pm4$ mV for LT1004-1.2
 - $-\pm20$ mV for LT1004-2.5
- Micropower Operation
- Operates up to 20 mA
- Very Low Reference Impedance
- Applications:
 - Portable Meter Reference
 - Portable Test Instruments
 - Battery-Operated Systems
 - Current-Loop Instrumentation

description/ordering information

The LT1004 micropower voltage reference is a two-terminal band-gap reference diode designed to provide high accuracy and excellent temperature characteristics at very low operating currents. Optimizing the key parameters in the design, processing, and testing of the device results in specifications previously attainable only with selected units.

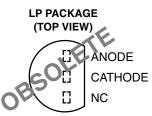


D OR PW PACKAGE

NC – No internal connection Terminals 6 and 8 are internally connected.

5

NC



NC - No internal connection

The LT1004 is a pin-for-pin replacement for the LM285 and LM385 series of references, with improved specifications. It is an excellent device for use in systems in which accuracy previously was attained at the expense of power consumption and trimming.

The LT1004C is characterized for operation from 0°C to 70°C. The LT1004I is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



LT1004-1.2, LT1004-2.5 MICROPOWER INTEGRATED VOLTAGE REFERENCES

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description/ordering information (continued)

ORDERING INFORMATION[†]

T _A	V _Z TYP	PACKAGE [‡]		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
		0010 (P)	Tube of 75	LT1004CD-1-2	40.40	
	401/	SOIC (D)	Reel of 2500	LT1004CDR-1-2	4C-12	
	1.2 V	TOCOR (DM)	Tube of 150	LT1004CPW-1-2	40.40	
000 to 7000		TSSOP (PW)	Reel of 2000	LT1004CPWR-1-2	4C-12	
0°C to 70°C		0010 (P)	Tube of 75	LT1004CD-2-5	40.05	
	0.51/	SOIC (D)	Reel of 2500	LT1004CDR-2-5	4C-25	
	2.5 V	TOOOD (DM)	Tube of 150	LT1004CPW-2-5	40.05	
		TSSOP (PW)	Reel of 2000	LT1004CPWR-2-5	4C-25	
		COIC (D)	Tube of 75	LT1004ID-1-2	41.40	
	401/	SOIC (D)	Reel of 2500	LT1004IDR-1-2	4l-12	
	1.2 V	TOCOD (DM)	Tube of 150	LT1004IPW-1-2	41.40	
-40°C to 85°C		TSSOP (PW)	Reel of 2000	LT1004IPWR-1-2	4l-12	
-40°C to 85°C		COIC (D)	Tube of 75	LT1004ID-2-5	11.05	
	2.5 V	SOIC (D)	Reel of 2500	LT1004IDR-2-5	41-25	
	2.5 V	TSSOP (PW)	Tube of 150	LT1004IPW-2-5	41-25	
		1000F (FW)	Reel of 2000	LT1004IPWR-2-5	41-20	

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

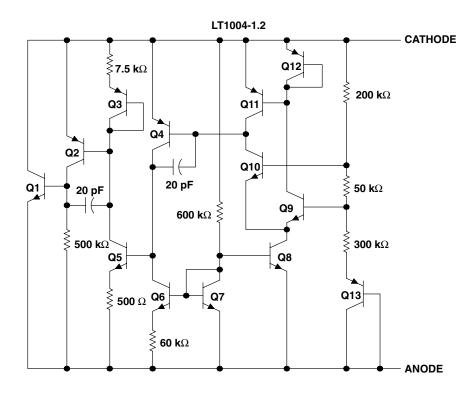
symbol

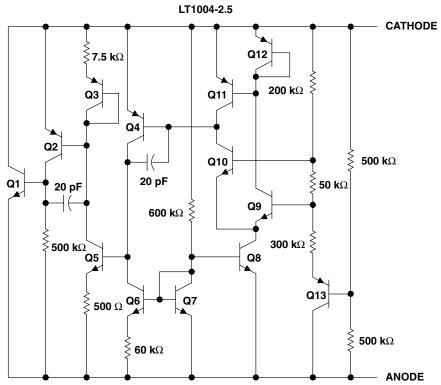




[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

schematic





NOTE A: All component values shown are nominal.



LT1004-1.2, LT1004-2.5 **MICROPOWER INTEGRATED VOLTAGE REFERENCES**

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Reverse current, I _R	30 mA
Forward current, I _F	10 mA
Package thermal impedance, θ _{JA} (see Notes 1 and 2): D package	97°C/W
PW package	149°C/W
Operating virtual junction temperature, T _J	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stg}	–65°C to 150°C

- NOTES: 1. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			MIN	MAX	UNIT
_	Operating free air temperature	LT1004C	0	70	<u>ې</u>
IA	Operating free-air temperature	LT1004I	-40	85	٠.

electrical characteristics at specified free-air temperature

	24244555	TEST			Ľ	Γ1004-1.	2	LT	1004-2.	5	
	PARAMETER	CONDITIONS T _A [‡]		MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
			2	25°C	1.231	1.235	1.239	2.48	2.5	2.52	
VZ	Reference voltage	$I_Z = 100 \mu A$	Full	LT1004C	1.225		1.245	2.47		2.53	V
			range	LT1004I	1.225		1.245	2.47		2.53	
g.,	Average	$I_Z = 10 \mu A$] ,	NE00		20					/0 C
α_{V_Z}	temperature coefficient of reference voltage§	I _Z = 20 μA	2	25°C					20		ppm/°C
		I I (min) to 1 m A	o 1 mA 25°C Full range				1			1	
 	Change in	$I_Z = I_Z(min)$ to 1 mA					1.5			1.5	
ΔV_Z	reference voltage with current	1 m A to 00 m A	25°C				10			10	mV
		$I_Z = 1 \text{ mA to } 20 \text{ mA}$	Full range				20			20	
$\Delta V_{Z}/\Delta t$	Long-term change in reference voltage	I _Z = 100 μA	2	25°C		20			20		ppm/khr
I _Z (min)	Minimum reference current		Ful	l range		8	10		12	20	μΑ
	.		2	25°C		0.2	0.6		0.2	0.6	
Z _Z	Reference impedance	$I_Z = 100 \mu A$	Full range		1.5		1.5		Ω		
V _n	Broadband noise voltage	I _Z = 100 μA, f = 10 Hz to 10 kHz	2	25°C		60			120		μV

[‡] Full range is 0°C to 70°C for the LT1004C and -40°C to 85°C for the LT1004I.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] The average temperature coefficient of reference voltage is defined as the total change in reference voltage divided by the specified temperature range.

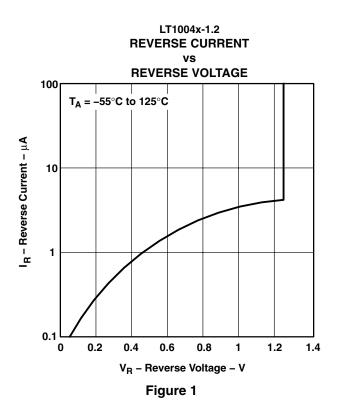
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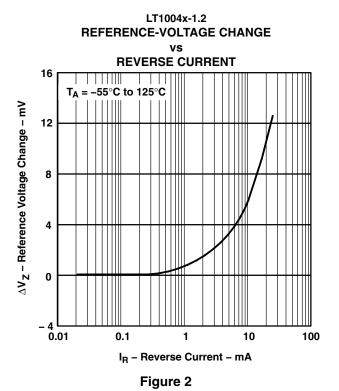
TYPICAL CHARACTERISTICS

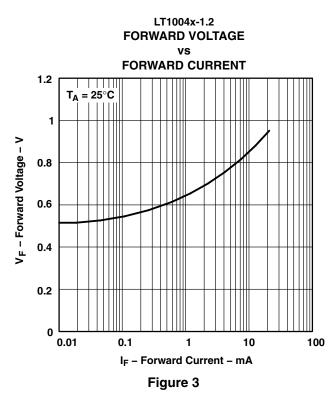
Table of Graphs

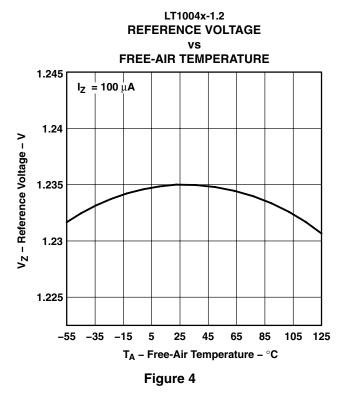
GRAPH TITLE	FIGURE
LT1004x-1.2	
Reverse current vs Reverse voltage	1
Reference-voltage change vs Reverse current	2
Forward voltage vs Forward current	3
Reference voltage vs Free-air temperature	4
Reference impedance vs Reference current	5
Noise voltage vs Frequency	6
Filtered output noise voltage vs Cutoff frequency	7
LT1004x-2.5	
Transient response	8
Reverse current vs Reverse voltage	9
Forward voltage vs Forward current	10
Reference voltage vs Free-air temperature	11
Reference impedance vs Reference current	12
Noise voltage vs Frequency	13
Filtered output noise voltage vs Cutoff frequency	14
Transient response	15





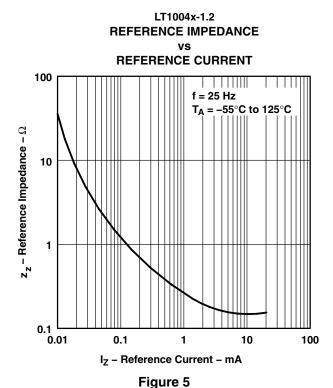


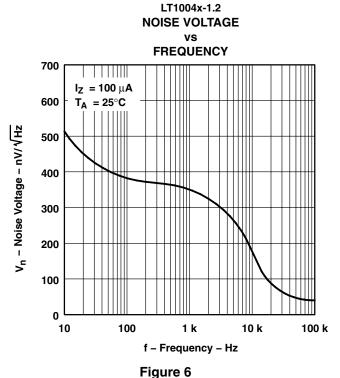




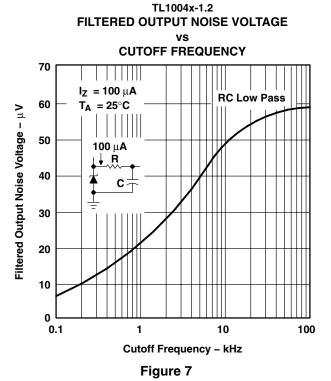
[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

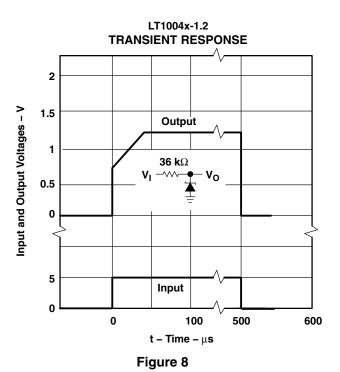






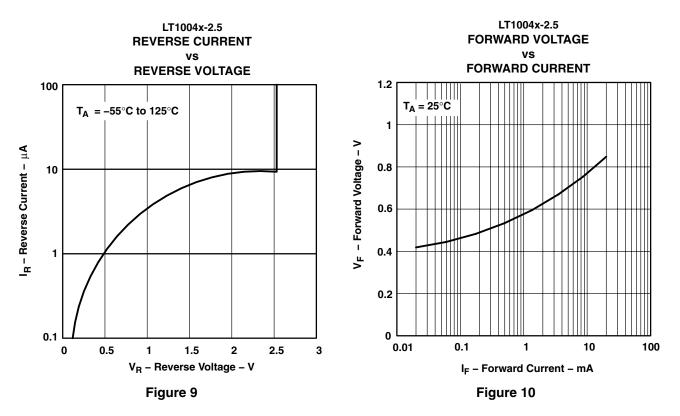
i iguie 3



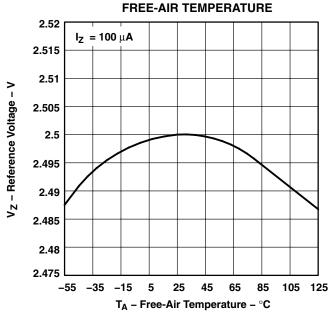


[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.





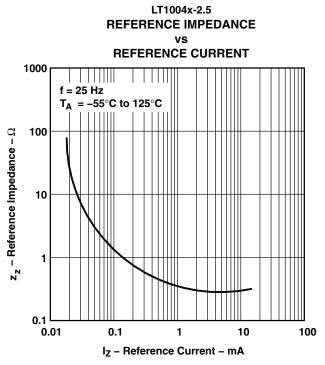
LT1004x-2.5 REFERENCE VOLTAGE vs



[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



Figure 11

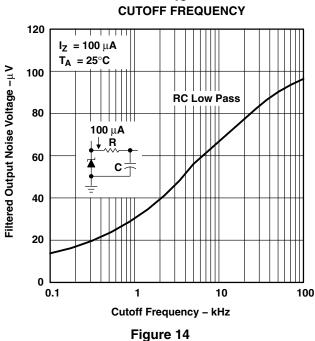


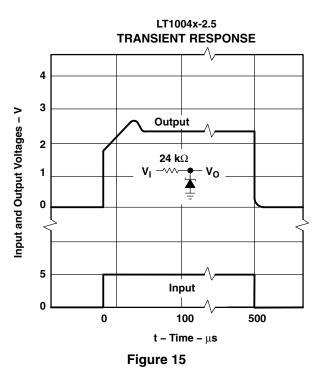
LT1004x-2.5 **NOISE VOLTAGE** ٧S **FREQUENCY** 1400 $I_Z = 100 \mu A$ = 25°C 1200 V_n - Noise Voltage - nV/VHz 1000 800 600 400 200 10 100 1 k 10 k 100 k f - Frequency - Hz

Figure 13

Figure 12

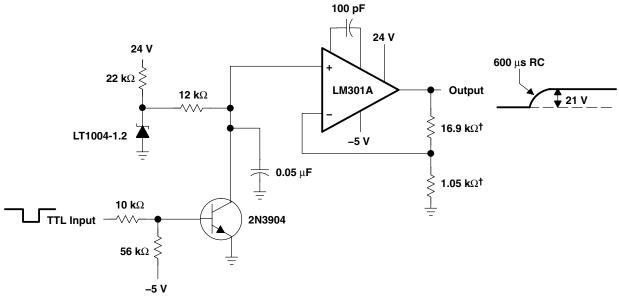
TL1004x-2.5
FILTERED OUTPUT NOISE VOLTAGE
VS
CUTOFF FREQUENCY





[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.





† 1% metal-film resistors

Figure 16. V_{I(PP)} Generator for EPROMs (No Trim Required)

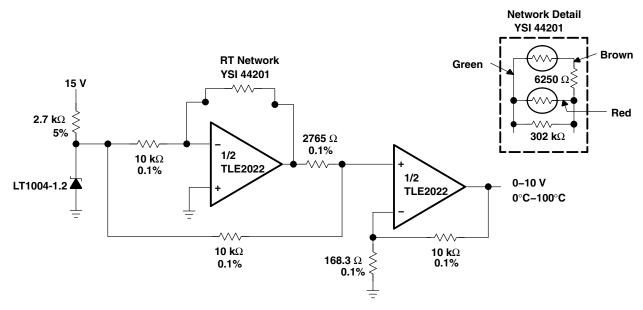


Figure 17. 0°C-to-100°C Linear-Output Thermometer

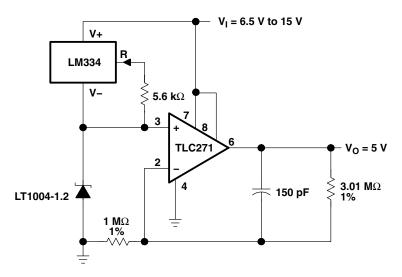
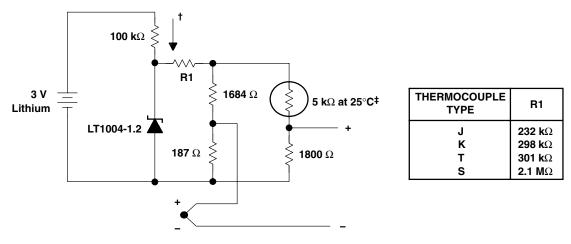


Figure 18. Micropower 5-V Reference



Figure 19. Low-Noise Reference

Figure 20. Micropower Reference From 9-V Battery



[†] Quiescent current \cong 15 μ A

NOTE A: This application compensates within $\pm 1^{\circ}$ C from 0° C to 60° C.

Figure 21. Micropower Cold-Junction Compensation for Thermocouples



[‡] Yellow Springs Inst. Co., Part #44007

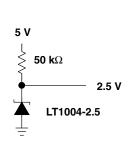


Figure 22. 2.5-V Reference

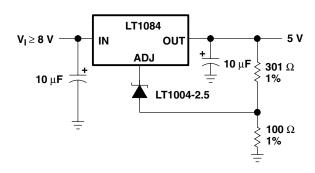
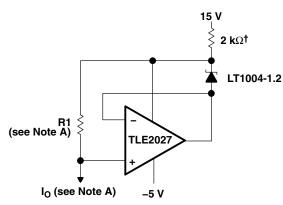


Figure 23. High-Stability 5-V Regulator

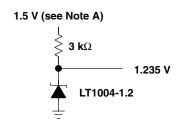


 † May be increased for small output currents NOTE A: R1 $\approx \frac{2~V}{I_O + 10~\mu A}$, $I_O = \frac{1.235~V}{R1}$

 $250 \text{ k}\Omega$ $250 \text{ k}\Omega$ $200 \text{ k}\Omega$ $200 \text{ k}\Omega$ $200 \text{ k}\Omega$ $V_{CC+} \ge 5 \text{ V}$

Figure 25. Amplifier With Constant Gain Over Temperature

Figure 24. Ground-Referenced Current Source



NOTE A: Output regulates down to 1.285 V for $I_O = 0$.

Figure 26. 1.2-V Reference From 1.5-V Battery

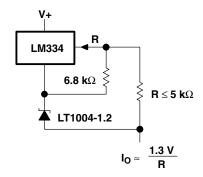
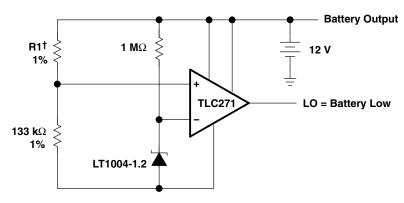


Figure 27. Terminal Current Source With Low Temperature Coefficient





 $^{^{\}dagger}$ R1 sets trip point, 60.4 k Ω per cell for 1.8 V per cell.

Figure 28. Lead-Acid Low-Battery-Voltage Detector

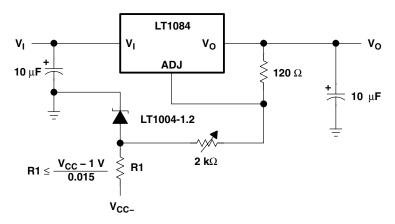


Figure 29. Variable-Voltage Supply





6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LT1004CD-1-2	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM		4C-12	Samples
LT1004CD-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM		4C-25	Samples
LT1004CDR-1-2	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM		4C-12	Samples
LT1004CDR-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM		4C-25	Samples
LT1004CDRG4-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	4C-25	Samples
LT1004CPW-1-2	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	4C-12	Samples
LT1004CPWR-1-2	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	4C-12	Samples
LT1004CPWR-2-5	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	4C-25	Samples
LT1004ID-1-2	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM		4I-12	Samples
LT1004ID-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM		41-25	Samples
LT1004IDG4-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	41-25	Samples
LT1004IDR-1-2	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	4I-12	Samples
LT1004IDR-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM		41-25	Samples
LT1004IDRE4-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	41-25	Samples
LT1004IDRG4-1-2	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	4I-12	Samples
LT1004IPW-1-2	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	4I-12	Samples
LT1004IPW-2-5	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	41-25	Samples



PACKAGE OPTION ADDENDUM

6-Feb-2020

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LT1004IPWR-1-2	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	41-12	Samples
LT1004IPWR-2-5	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	41-25	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
E	30	Dimension designed to accommodate the component length
K	(0	Dimension designed to accommodate the component thickness
	N	Overall width of the carrier tape
F	21	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LT1004CDR-1-2	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LT1004CDR-1-2	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LT1004CDR-2-5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LT1004CPWR-1-2	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LT1004CPWR-2-5	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LT1004IDR-1-2	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LT1004IDR-2-5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LT1004IPWR-1-2	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LT1004IPWR-2-5	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LT1004CDR-1-2	SOIC	D	8	2500	367.0	367.0	35.0
LT1004CDR-1-2	SOIC	D	8	2500	340.5	338.1	20.6
LT1004CDR-2-5	SOIC	D	8	2500	340.5	338.1	20.6
LT1004CPWR-1-2	TSSOP	PW	8	2000	367.0	367.0	35.0
LT1004CPWR-2-5	TSSOP	PW	8	2000	367.0	367.0	35.0
LT1004IDR-1-2	SOIC	D	8	2500	340.5	338.1	20.6
LT1004IDR-2-5	SOIC	D	8	2500	340.5	338.1	20.6
LT1004IPWR-1-2	TSSOP	PW	8	2000	367.0	367.0	35.0
LT1004IPWR-2-5	TSSOP	PW	8	2000	367.0	367.0	35.0



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



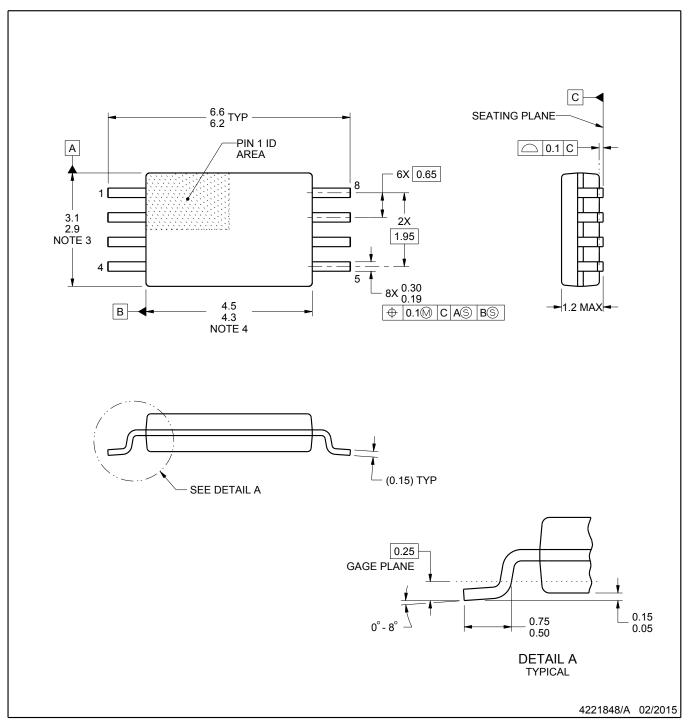
NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.





SMALL OUTLINE PACKAGE



NOTES:

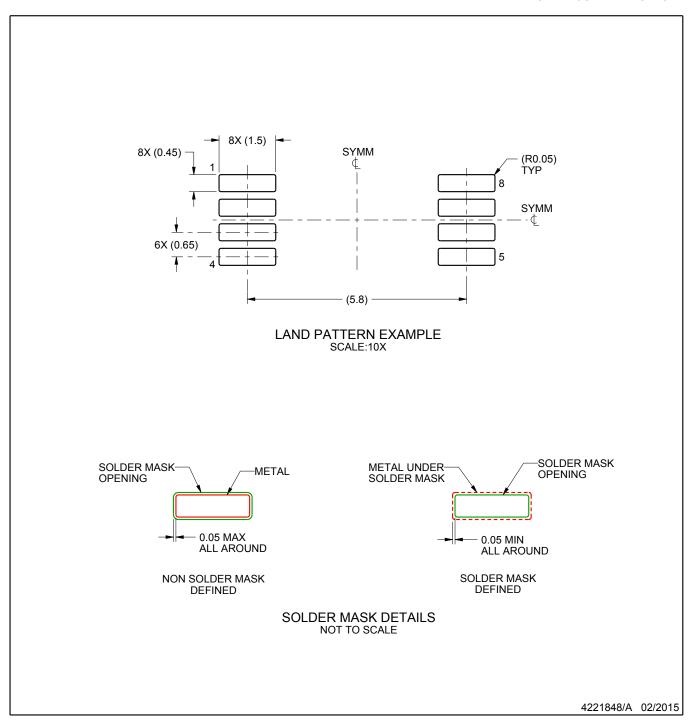
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153, variation AA.



SMALL OUTLINE PACKAGE



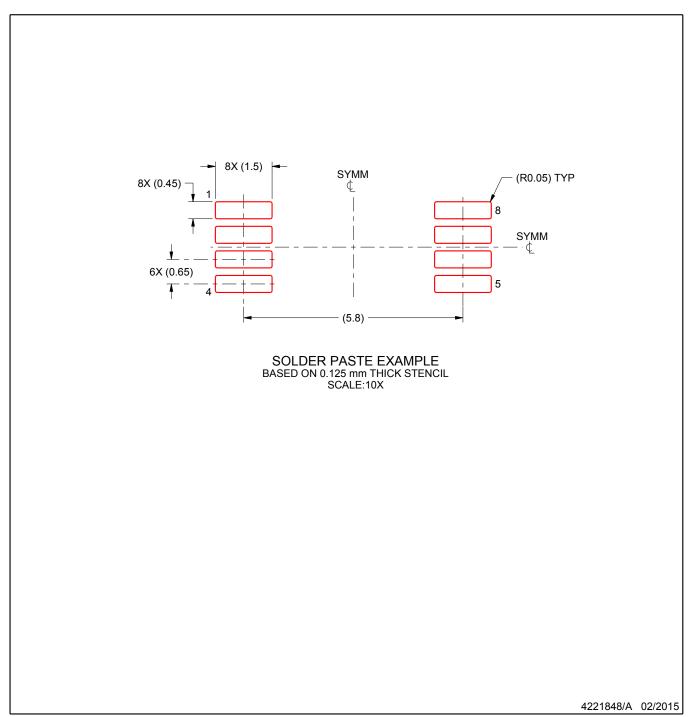
NOTES: (continued)

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SMALL OUTLINE PACKAGE



NOTES: (continued)

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